

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7093	((438/106) or (438/113) or (438/114) or (438/118) or (438/459)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 09:00
L2	755	(wafer or substrate) near8 (singulat\$4 or separat\$4 or dicing) same (adhesive) same tape same (street or (scribe near line) or cut or mark or marked or marking or indentation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 09:26
L3	123	L1 and L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 09:00
L4	81	L3 and ((@ad<"20020627") or (@rlad<"20020627"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 09:00
L5	4079	(wafer or substrate or carrier or holder or support\$4) near8 (singulat\$4 or separat\$4 or dicing or cut\$4) same (adhesive or seal\$4) same tape same (street or (scribe near line) or cut or mark or marked or marking or indentation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 09:27
L6	192	5 and (passivat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:40
L7	1677	(438/118).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 10:41
L8	3235010	(tape or protect\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:42

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L9	1156	7 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:42
L10	100145	(pad or bond\$4 or island) near8 (passivation or insulat\$4 or interlayer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:43
L11	302	9 and 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:43
L12	1043	(438/459).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 10:50
L13	55	L12 and (tape or protection or protected or protecting) and (adhesive or sealant) and (passivation or passivating or passivated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:51
L14	1126	257/730	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:52
L15	12	14 and (bonding pad) and passivation and (wafer substrate holder carrier board support\$4) and (adhesive sealant) and (polish\$4 CMP)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:53
L16	2811	(tape near2 polymer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:55

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L17	52	L16 with (die chip) with (substrate wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:55
L18	131	L16 with (die IC dice element component package chip) with (substrate carrier holder support\$4 board wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 10:56

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L1	6350	(CMP or polish\$4 or grind\$4 or abras\$4) near8 (rear backside bottom) near8 (wafer substrate holder carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 13:53
L2	3935879	(buffer or coat\$4 or photosensitive or photoresist or resist or photo-mask or photo-resist)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 13:54
L3	769327	(passivation or passivating or SiN or (silicon near nitride) or (silicon near oxide) or "SiO.sub.2" or (silicon near dioxide))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 13:55
L4	69153	(passivation or passivating or SiN or (silicon near nitride) or (silicon near oxide) or "SiO.sub.2" or (silicon near dioxide)) near8 (pad contact conductor conductive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 13:56
L5	599	1 and 2 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:18
L6	955	(257/730).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 14:18
L7	10	6 and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:18
L8	35	6 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:20

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L9	35	8 not 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:21
L10	1198	(257/783).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 14:22
L11	1184	10 not 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:22
L12	13	11 and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:22
L13	835560	MATSUSHITA.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:23
L14	78643	Seo.in. or Matsuda.in. or Minamide.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:23
L15	3	13 and (passivation same (apertures opening via vias) same (bonding near pad) same (buffer near coat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:25
L16	3	14 and (passivation same (apertures opening via vias) same (bonding near pad) same (buffer near coat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:25

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L17	1043	(438/459).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 14:26
L18	10	("3809050" "3849948" "4722130" "5494549" "5851664" "5891298" "6059637" "6153536" "6503130" "6551447").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/15 14:28
L19	417	(((bond\$6 near2 pad) same (aperture or via or opening or hole or gap or through-hole or (through adj hole)) same (buffer\$4 or photoresist or PR or resist)) same (wafer or substrate)) and (polish\$6 or CMP or "chemical mechanical polishing")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 14:47

EAST Search History

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L1	417	((bond\$6 near2 pad) same (aperture or via or opening or hole or gap or through-hole or (through adj hole)) same (buffer\$4 or photoresist or PR or resist)) same (wafer or substrate)) and (polish\$6 or CMP or "chemical mechanical polishing")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 16:55
L2	163	((438/106).CCLS.) and ((polish\$6 or grind\$6 or dispers\$6 or abras\$6) near4 wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 19:24
L3	1677	(438/118).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 19:24
L4	118	3 and ((polish\$6 or grind\$6 or dispers\$6 or abras\$6) near4 wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 19:24
L5	1	((bond\$4 or contact) near2 pads) and (wafer or substrate or carrier or holder or board) and (scribe or street or lane or cut or cutting or dicing or sawing or singulat\$4 or separat\$4) and (buffer near2 coat\$4) and (adhesive or sealant) and (tape or protection or cap or capping) and (CMP or polish\$4 or grind\$4 or slurry or abrasive)). clm.	US-PGPUB	OR	ON	2006/12/15 20:09